



TG-N8000 Non-silicone Thermal Putty

REACH Compliant

RoHS Compliant

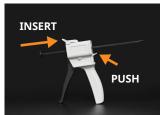
Features

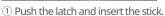
- · Silicone free thermal gel
- · Lower contact thermal impedance than thermal pads
- · Physical property in between liquid and solid state
- · Gap fillers for uneven or irregular surfaces of heat sources and heat sink
- · Applicable for dispenser

Applications

Electronic Components - 5G, Aerospace, AI, AIoT, AR/VR/MR/XR, Automotive, Consumer Devices, Datacom, Electric Vehicle, Electronic Products, Energy Storage, Industrial, Lighting Equipment, Medical, Military, Netcom, Panel, Power Electronics, Robot, Servers, Smart Home, Telecom, etc.

Operation Manual







2 Put the tube in and twist.



③ Close the cover.



4 Take off the plug.

(The putty in the picture does not represent the actual product.)

Properties

Thermal Conductivity: 8.0 W/m·K

0 0.8 1.2 1.4 1.6 1.7 1.8 2.2 3.2 3.6 4.0 4.5 5.0 15 20

Properties	Unit	TG-N8000	Tolerance	Test Method
Thermal Conductivity	W/m·K	8.0	-	ASTM D5470 Modified
Color	-	Yellow	-	-
Viscosity	Pa∙s	430	±100	Brookfield Viscometer
Density	g/cm³	3	±0.15	ASTM D792
Volume Resistivity	Ohm∙m	>1010	-	ASTM D257
Operating Temperature	° C	-40~+125	-	-
Standard Package	-	Tube/ Pot	-	-

T-Global Techonology Co., Ltd.

No.33, Ln.50, Daren Rd., Taoyuan Dist., Taoyuan City 330058, Taiwan

T +886-3-361-8899 E service@tglobalcorp.com

W www.tglobalcorp.com



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